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### (54) SYSTEMS AND METHODS FOR TEMPERATURE PROFILE CONTROL OF MICROWAVE OVEN DEVICES

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#### ABSTRACT (57)

A method by an electromagnetic device includes determining a pattern of electromagnetic energy absorbed by a load disposed inside a cavity into which electromagnetic radiation is directed and generating one or more maps of the pattern of electromagnetic energy absorbed by the load. The one or more maps comprises an indication of a distribution of heating within the load. The method further includes determining, based on the one or more maps, a plurality of sequences of operating parameter combinations configured so as to heat the load via absorption of the electromagnetic radiation in accordance with a target temperature profile with respect to the load. The method thus includes emitting electromagnetic radiation into the cavity based on the plurality of sequences of operating parameter combinations to achieve the target temperature profile with respect to the load

- 100 RF & MICROWAVE MEMORY DISPLAY 112 118 ELECTRONICS 106 114 104 108-<u>-</u> 102 MPUT SENSORS PROCESSORIS' STRUCTURES -118 120 POWER NETWORK 10 116 SOURCE INTERFACE INTERFACE 102 MICROWAVE OVEN DEVICE